



# Product End-of-Life Disassembly Instructions

Product Category: Consumer Notebook

Marketing Name / Model

[List multiple models if applicable.]

HP Pavilion Chromebook 14 PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm USB board, Wireless module ,SSD module, Touchpad module, Touchpad board , Memory module*2,Mother board	7
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin cell battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #Screwdriver	
Description #2	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release screws in bottom side of base case (figure 9)
2. Release KeyBoard (figure 10)
3. Release screws under KeyBoard and power FFC/ TP FFC
4. Release TOP assy (figure 11)
5. Release Hinge screws and Remove LVDS cable & antenna cable and LCD ASSY (figure 12)
6. Remove FAN cable/ speaker cable and DC cable
7. Release screws and remove USB board (figure 13)
8. Release screws and remove HDD (figure 14)
9. Release screws and remove wireless card, (figure 15)
10. Remove DCin cable
11. Release screw and remove MB PCB (figure 16)
12. Release screws and remove heat pipe, PCH bkt, SSD module & RAM module (figure 17)
13. Remove Power board and TP board (figure 18)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Power board



2. Wireless module



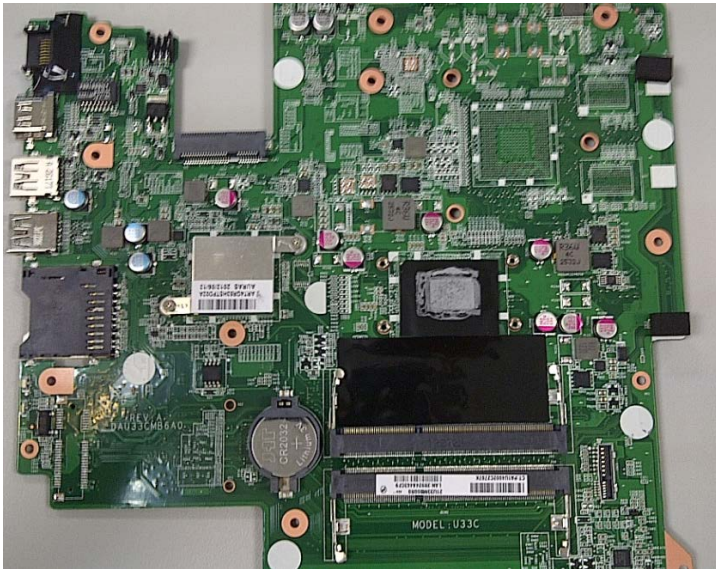
3. USB board



4. RAM module



5. Mother board



6.



7.



8.





